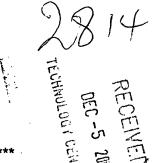


# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



### PATENT APPLICATION

## **INVENTORS:**

Yinon Degani Thomas Dixon Dudderar Liguo Sun Meng Zhao

CASE: 60-40-1-1

TITLE: STACKED MODULE PACKAGE

**SERIAL NO.** 09/964,009

**FILING DATE 09/14/00** 

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**EXAMINER** DiLinh P. Nguyen

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### SIR:

In response to the Office action mailed 08/28/2002 please enter the following amendments and consider the remarks that follow.

In the claims:

Please amend claim 1 to read:



1. A stacked MCM package comprising a substrate, a digital MCM on the substrate, an RF MCM on the digital MCM, and means electrically connecting the RF MCM to the substrate, and wherein the RF MCM and the digital MCM are electrically isolated.